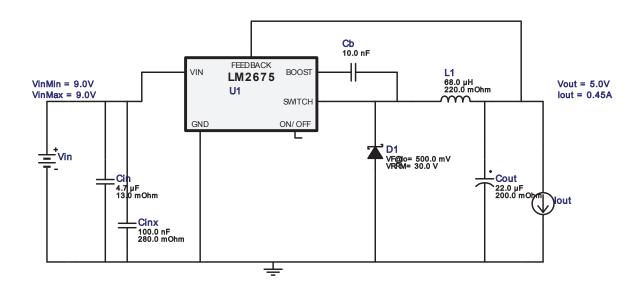


WEBENCH® Design Report

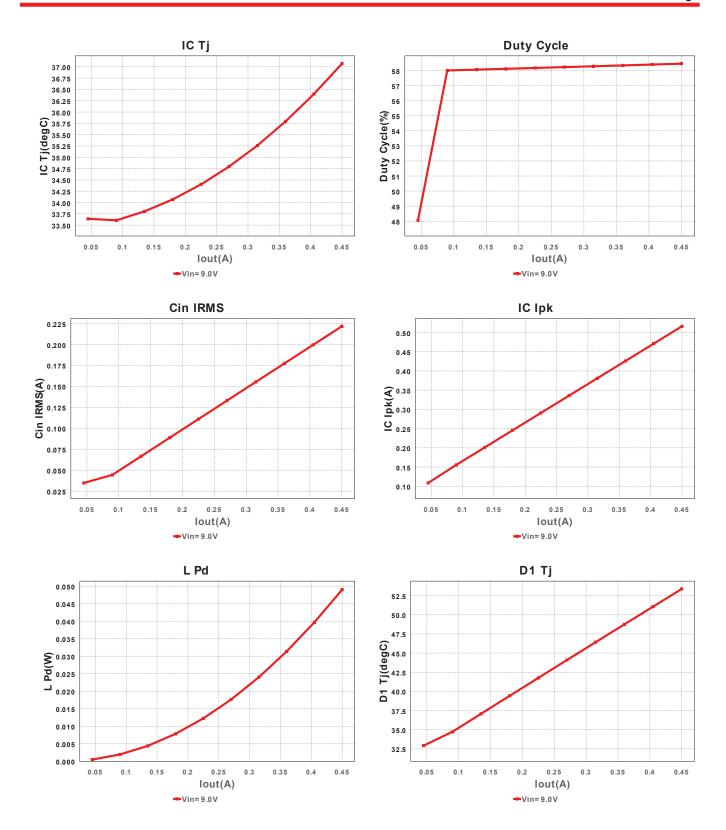
VinMin = 9.0V Device = LM2675M-5.0/NOPB
VinMax = 9.0V Topology = Buck
Vout = 5.0V Created = 10/14/13 11:50:56 AM
BOM Cost = \$2.50
Total Pd = 0.21W
Footprint = 335.0mm2
BOM Count = 7

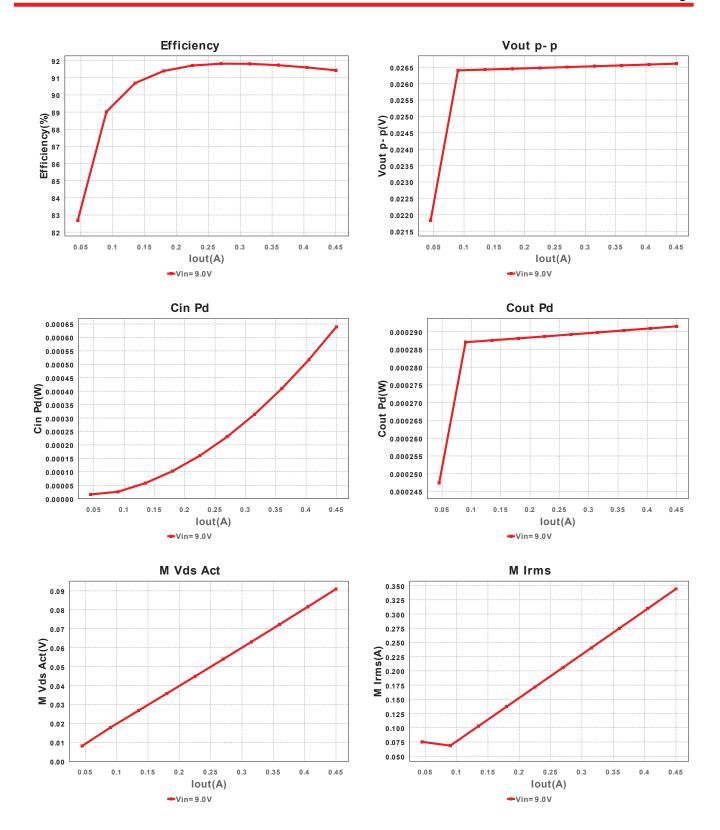
Design: 3867961/16 LM2675M-5.0/NOPB LM2675M-5.0/NOPB 9.0V-9.0V to 5.0V @ 0.45A

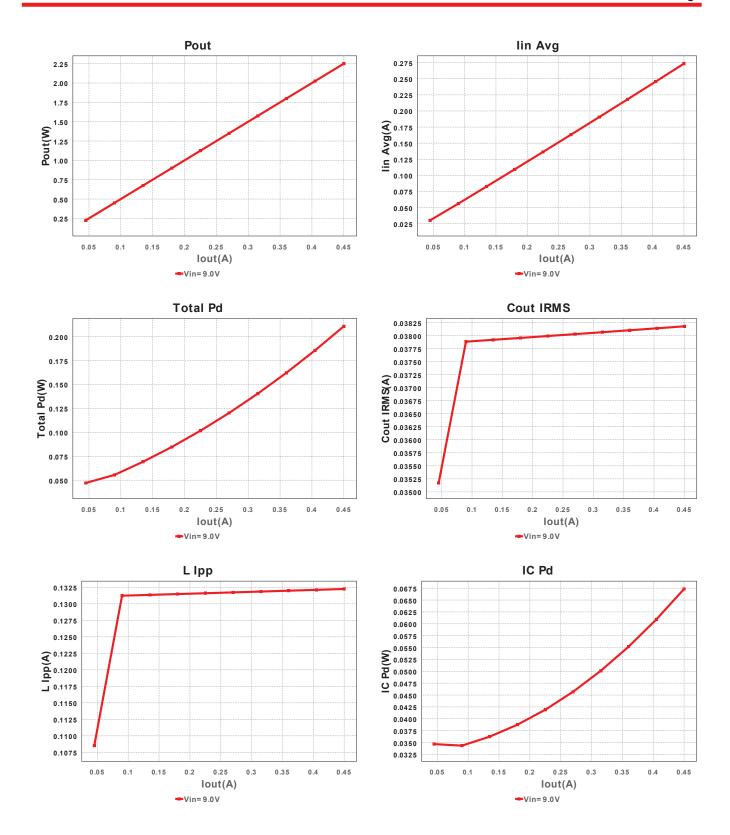


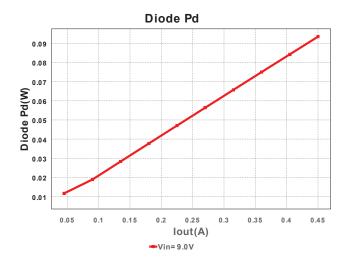
## **Electrical BOM**

#	Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
1.	Cb	MuRata	GRM216R71H103KA01D Series= X7R	Cap= 10.0 nF VDC= 50.0 V IRMS= 0.0 A	1	\$0.01	0805 7mm2
2.	Cin	Kemet	C1206C475K4PACTU Series= X5R	Cap= 4.7 μF ESR= 13.0 mOhm VDC= 16.0 V IRMS= 4.9 A	1	\$0.04	1206 11mm2
3.	Cinx	AVX	08053C104KAT2A Series= X7R	Cap= 100.0 nF ESR= 280.0 mOhm VDC= 25.0 V IRMS= 0.0 A	1	\$0.01	0805 7mm2
4.	Cout	Vishay-Sprague	593D226X9025D2TE3 Series= 593D	Cap= 22.0 μF ESR= 200.0 mOhm VDC= 25.0 V IRMS= 870.0 mA	1	\$0.51	7343-31 59mm2
5.	D1	Diodes Inc.	B130-13-F	VF@Io= 500.0 mV VRRM= 30.0 V	1	\$0.06	SMA 37mm2
6.	L1	Bourns	SDR1006-680KL	L= 68.0 μH DCR= 220.0 mOhm	1	\$0.27	SDR1006 139mm2
7.	U1	Texas Instruments	LM2675M-5.0/NOPB	Switcher	1	\$1.60	M08A 55mm2









## **Operating Values**

operating values							
#	Name	Value	Category	Description			
1.	BOM Count	7		Total Design BOM count			
2.	Total BOM	\$2.496		Total BOM Cost			
3.	Cin IRMS	221.76 mA	Current	Input capacitor RMS ripple current			
4.	Cout IRMS	38.177 mA	Current	Output capacitor RMS ripple current			
5.	IC lpk	516.125 mA	Current	Peak switch current in IC			
6.	lin Avg	273.42 mA	Current	Average input current			
7.	L lpp	132.25 mA	Current	Peak-to-peak inductor ripple current			
8.	M1 Irms	344.05 mA	Current	Q lavg			
9.	FootPrint	335.0 mm2	General	Total Foot Print Area of BOM components			
10.	Frequency	260.0 kHz	General	Switching frequency			
11.	IC Tolerance	0.0 V	General	IC Feedback Tolerance			
12.	M Vds Act	90.996 mV	General	Voltage drop across the MosFET			
13.	Pout	2.25 W	General	Total output power			
14.	D1 Tj	53.369 degC	Op_Point	D1 junction temperature			
15.	Vout OP	5.0 V	Op_Point	Operational Output Voltage			
16.	Cross Freq	61.205 kHz	Op_point	Bode plot crossover frequency			
17.	Duty Cycle	58.455 %	Op_point	Duty cycle			
18.	Efficiency	91.436 %	Op_point	Steady state efficiency			
19.	IC Tj	37.07 degC	Op_point	IC junction temperature			
20.	ICThetaJA	105.0 degC/W	Op_point	IC junction-to-ambient thermal resistance			
21.	IOUT_OP	450.0 mA	Op_point	lout operating point			
22.	Phase Marg	56.122 deg	Op_point	Bode Plot Phase Margin			
23.	VIN_OP	9.0 V	Op_point	Vin operating point			
24.	Vout p-p	26.607 mV	Op_point	Peak-to-peak output ripple voltage			
25.	Cin Pd	639.308 μW	Power	Input capacitor power dissipation			
26.	Cout Pd	291.502 μW	Power	Output capacitor power dissipation			
27.	Diode Pd	93.477 mW	Power	Diode power dissipation			
28.	IC Pd	67.33 mW	Power	IC power dissipation			
29.	L Pd	49.005 mW	Power	Inductor power dissipation			
30.	Total Pd	210.741 mW	Power	Total Power Dissipation			

## **Design Inputs**

	5 1 2 2 2		
#	Name	Value	Description
1.	lout	450.0 mA	Maximum Output Current
2.	lout1	450.0 mAmps	Output Current #1
3.	VinMax	9.0 V	Maximum input voltage
4.	VinMin	9.0 V	Minimum input voltage
5.	Vout	5.0 V	Output Voltage
6.	Vout1	5.0 Volt	Output Voltage #1
7.	base_pn	LM2675	Base Product Number
8.	source	DC	Input Source Type
9.	Та	30.0 degC	Ambient temperature

## Design Assistance

1. **LM2675** Product Folder: http://www.ti.com/product/lm2675: contains the data sheet and other resources.

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